



2PD601ARL; 2PD601ASL

50 V, 100 mA NPN general-purpose transistors

Rev. 01 — 6 November 2008

Product data sheet

1. Product profile

1.1 General description

NPN general-purpose transistors in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

Table 1. Product overview

| Type number ^[1] | Package | | PNP complement |
|----------------------------|---------|----------|----------------|
| | NXP | JEDEC | |
| 2PD601ARL | SOT23 | TO-236AB | 2PB709ARL |
| 2PD601ASL | | | 2PB709ASL |
| 2PD601ARL/DG | SOT23 | TO-236AB | 2PB709ARL/DG |
| 2PD601ASL/DG | | | 2PB709ASL/DG |

[1] /DG: halogen-free.

1.2 Features

- General-purpose transistors
- Two current gain selections
- AEC-Q101 qualified
- Small SMD plastic package

1.3 Applications

- General-purpose switching and amplification

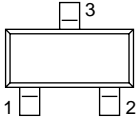
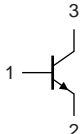
1.4 Quick reference data

Table 2. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------|---------------------------|--|-----|-----|-----|------|
| V_{CE0} | collector-emitter voltage | open base | - | - | 50 | V |
| I_C | collector current | | - | - | 100 | mA |
| h_{FE} | DC current gain | $V_{CE} = 10\text{ V};$ $I_C = 2\text{ mA}$ | | | | |
| | h_{FE} group R | | 210 | - | 340 | |
| | h_{FE} group S | | 290 | - | 460 | |

2. Pinning information

Table 3. Pinning

| Pin | Description | Simplified outline | Graphic symbol |
|-----|-------------|---|---|
| 1 | base |  |  sym021 |
| 2 | emitter | | |
| 3 | collector | | |

3. Ordering information

Table 4. Ordering information

| Type number ^[1] | Package | | |
|----------------------------|---------|--|---------|
| | Name | Description | Version |
| 2PD601ARL | - | plastic surface-mounted package; 3 leads | SOT23 |
| 2PD601ASL | | | |
| 2PD601ARL/DG | | | |
| 2PD601ASL/DG | | | |

[1] /DG: halogen-free.

4. Marking

Table 5. Marking codes

| Type number | Marking code ^[1] |
|--------------|-----------------------------|
| 2PD601ARL | SM* |
| 2PD601ASL | SK* |
| 2PD601ARL/DG | SR* |
| 2PD601ASL/DG | SY* |

[1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|---------------------------|----------------------------------|-------|------|------|
| V_{CBO} | collector-base voltage | open emitter | - | 60 | V |
| V_{CEO} | collector-emitter voltage | open base | - | 50 | V |
| V_{EBO} | emitter-base voltage | open collector | - | 6 | V |
| I_C | collector current | | - | 100 | mA |
| I_{CM} | peak collector current | single pulse; $t_p \leq 1$ ms | - | 200 | mA |
| I_{BM} | peak base current | single pulse; $t_p \leq 1$ ms | - | 100 | mA |
| P_{tot} | total power dissipation | $T_{amb} \leq 25$ °C | [1] - | 250 | mW |
| T_j | junction temperature | | - | 150 | °C |
| T_{amb} | ambient temperature | | -55 | +150 | °C |
| T_{stg} | storage temperature | | -65 | +150 | °C |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 7. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---------------|---|-------------|-------|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] - | - | 500 | K/W |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

7. Characteristics

Table 8. Characteristics

$T_{amb} = 25$ °C unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------|--------------------------------|---|----------------------------------|-----|-----|------|
| I_{CBO} | collector-base cut-off current | $V_{CB} = 60$ V; $I_E = 0$ A | - | - | 10 | nA |
| | | $V_{CB} = 60$ V; $I_E = 0$ A; $T_j = 150$ °C | - | - | 5 | μA |
| I_{EBO} | emitter-base cut-off current | $V_{EB} = 5$ V; $I_C = 0$ A | - | - | 10 | nA |
| h_{FE} | DC current gain | $V_{CE} = 2$ V; $I_C = 100$ mA | [1] 90 | - | - | |
| | | h_{FE} group R | $V_{CE} = 10$ V; $I_C = 2$ mA | 210 | - | 340 |
| | | h_{FE} group S | $V_{CE} = 10$ V; $I_C = 2$ mA | 290 | - | 460 |

Table 8. Characteristics ...continued
 $T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------|--------------------------------------|--|-------|-----|-----|------|
| V_{CEsat} | collector-emitter saturation voltage | $I_C = 100\text{ mA};$ $I_B = 10\text{ mA}$ | [1] - | - | 250 | mV |
| f_T | transition frequency | $V_{CE} = 10\text{ V};$ $I_C = 2\text{ mA};$ $f = 100\text{ MHz}$ | 100 | - | - | MHz |
| C_c | collector capacitance | $V_{CB} = 10\text{ V};$ $I_E = I_B = 0\text{ A};$ $f = 1\text{ MHz}$ | - | - | 3 | pF |

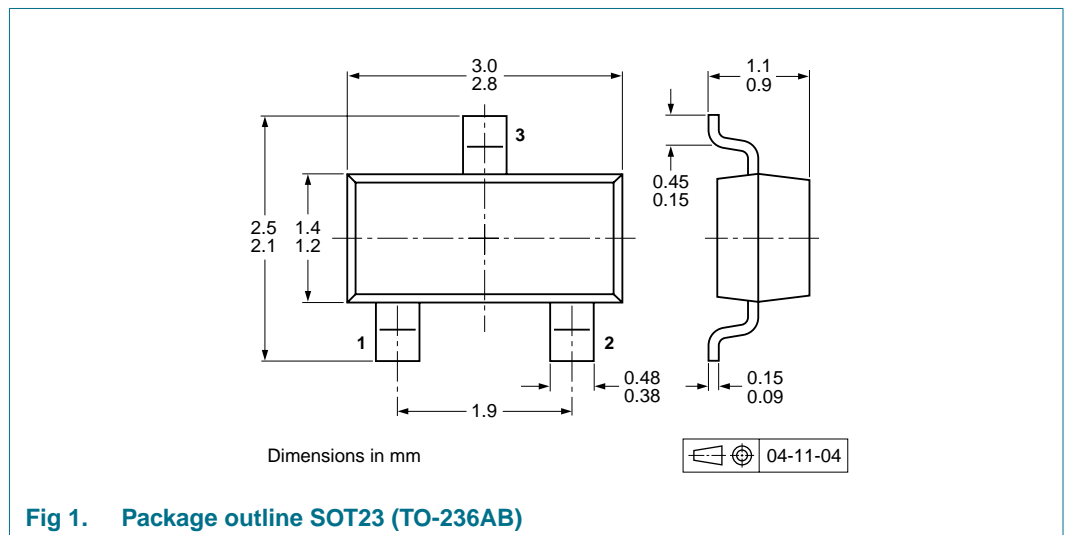
[1] Pulse test: $t_p \leq 300\ \mu\text{s}; \delta \leq 0.02$.

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline



10. Packing information

Table 9. Packing methods

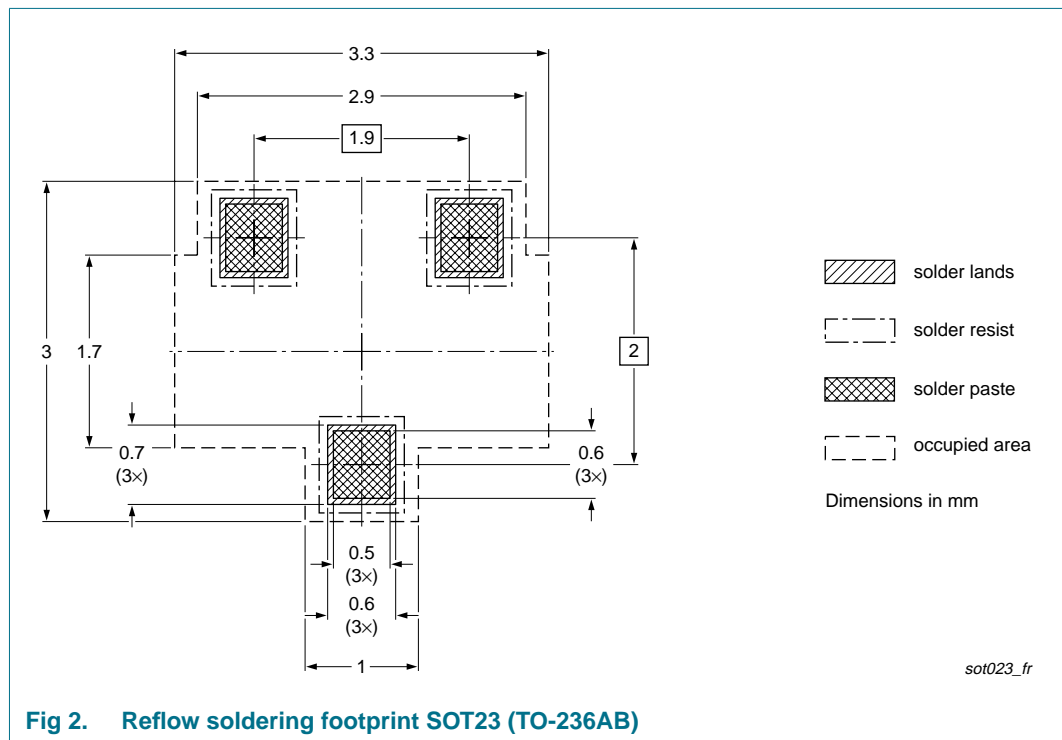
The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

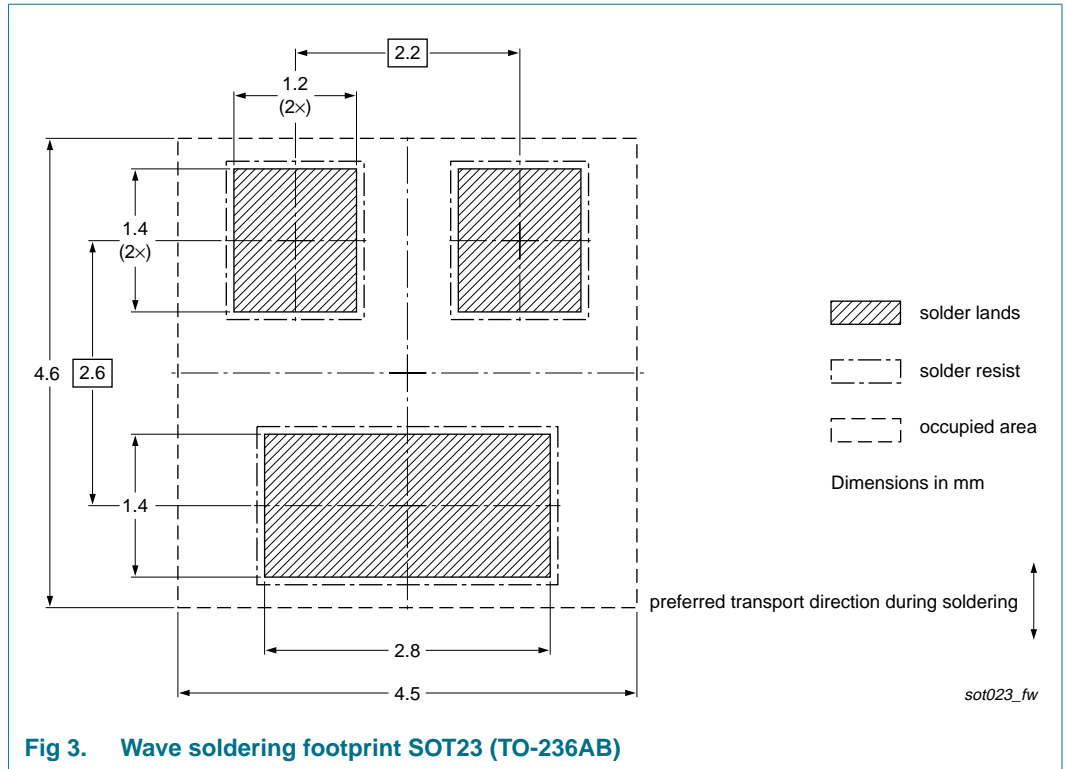
| Type number ^[2] | Package | Description | Packing quantity | |
|----------------------------|---------|--------------------------------|------------------|-------|
| | | | 3000 | 10000 |
| 2PD601ARL | SOT23 | 4 mm pitch, 8 mm tape and reel | -215 | -235 |
| 2PD601ASL | | | | |
| 2PD601ARL/DG | | | | |
| 2PD601ASL/DG | | | | |

[1] For further information and the availability of packing methods, see [Section 14](#).

[2] /DG: halogen-free.

11. Soldering





12. Revision history

Table 10. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-------------|--------------|--------------------|---------------|------------|
| 2PD601AXL_1 | 20081106 | Product data sheet | - | - |

13. Legal information

13.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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15. Contents

| | | |
|-----------|--------------------------------------|----------|
| 1 | Product profile | 1 |
| 1.1 | General description | 1 |
| 1.2 | Features | 1 |
| 1.3 | Applications | 1 |
| 1.4 | Quick reference data | 1 |
| 2 | Pinning information | 2 |
| 3 | Ordering information | 2 |
| 4 | Marking | 2 |
| 5 | Limiting values | 3 |
| 6 | Thermal characteristics | 3 |
| 7 | Characteristics | 3 |
| 8 | Test information | 4 |
| 8.1 | Quality information | 4 |
| 9 | Package outline | 4 |
| 10 | Packing information | 5 |
| 11 | Soldering | 5 |
| 12 | Revision history | 7 |
| 13 | Legal information | 8 |
| 13.1 | Data sheet status | 8 |
| 13.2 | Definitions | 8 |
| 13.3 | Disclaimers | 8 |
| 13.4 | Trademarks | 8 |
| 14 | Contact information | 8 |
| 15 | Contents | 9 |

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Date of release: 6 November 2008

Document identifier: 2PD601AXL_1

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